



Dual N-Channel Enhancement Mode Power MOSFET **MX9926**

## DESCRIPTION

The MX9926 uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge. It can be used in a wide variety of applications.

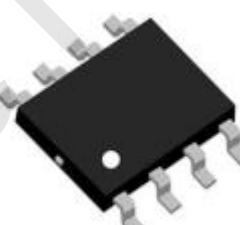
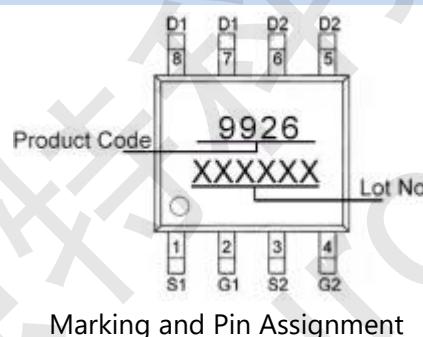
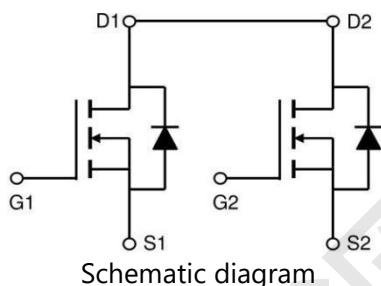
## GENERAL FEATURES

- $V_{DS}=20V$ ,  $I_D=6A$
- $R_{DS(ON)}(\text{Typ.})=32m\Omega$  @  $V_{GS}=2.5V$
- $R_{DS(ON)}(\text{Typ.})=24m\Omega$  @  $V_{GS}=4.5V$
- High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package

## APPLICATION

- Load switch
- Battery protection
- Power management

## PINOUT



Schematic diagram

Marking and Pin Assignment

SOP-8 top view

## ORDERING INFORMATION

Part Number	Storage Temperature	Package	Devices Per Reel
MX9926	-55°C to 150°C	SOP-8	-

## ABSOLUTE MAXIMUM RATINGS ( $T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Drain Current-Continuous	$I_D$	6	A
Drain Current-Continuous( $T_A=70^\circ C$ )	$I_D$	3.8	A
Pulsed Drain Current <sup>(Note1)</sup>	$I_{DM}$	25	A
Maximum Power Dissipation	$P_D$	1.25	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C

## THERMAL RESISTANCE

Thermal Resistance, Junction-to-Ambient <sup>(Note2)</sup>	$R_{\theta JA}$	100	°C/W
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Note 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Note 2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.



**ELECTRICAL CHARACTERISTICS**( $T_A=25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
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**Off Characteristics**

Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	20	-	-	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=20\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 12\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA

**On Characteristics**<sup>(Note 3)</sup>

Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	0.5	0.75	12	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=2.5\text{V}, I_{\text{D}}=5\text{A}$	-	32	38	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=6\text{A}$	-	24	28	$\text{m}\Omega$
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=6\text{A}$	20	-	-	S

**Dynamic Characteristics**<sup>(Note 4)</sup>

Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=10\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	640	-	pF
Output Capacitance	$C_{\text{oss}}$		-	140	-	pF
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	80	-	pF

**Switching Characteristics**

Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=10\text{V}, I_{\text{D}}=1\text{A}, R_{\text{L}}=1\Omega, V_{\text{GS}}=4.5\text{V}, R_{\text{G}}=6\Omega$	-	8	-	nS
Turn-on Rise Time	$t_{\text{r}}$		-	9	-	nS
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	15	-	nS
Turn-Off Fall Time	$t_{\text{f}}$		-	4	-	nS
Total Gate Charge	$Q_{\text{g}}$	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=3\text{A}, V_{\text{GS}}=4.5\text{V}$	-	10	-	nC
Gate-Source Charge	$Q_{\text{gs}}$		-	1.5	-	nC
Gate-Drain Charge	$Q_{\text{gd}}$		-	1.6	-	nC

**Drain-Source Diode Characteristics**

Diode Forward Voltage <sup>(Note 3)</sup>	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=1.7\text{A}$	-	-	1.2	V
Diode Forward Current <sup>(Note 2)</sup>	$I_{\text{S}}$		-	-	6	A

Note 2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.

Note 3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .

Note 4. Guaranteed by design, not subject to product.



## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 1. Switching Test Circuit

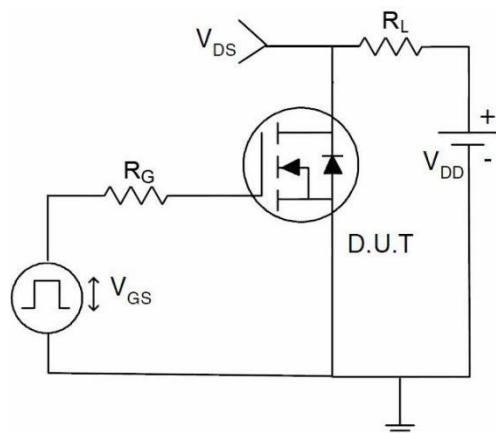


Figure 2. Switching Waveform

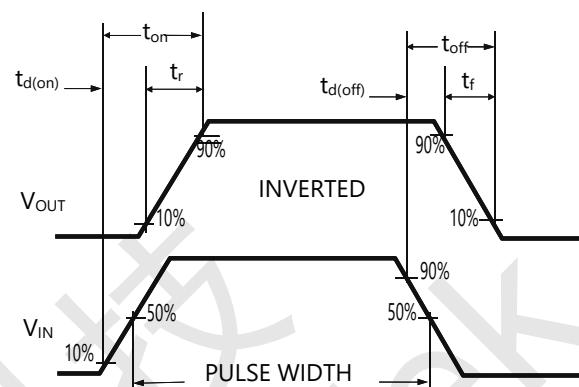


Figure 3. Power Dissipation

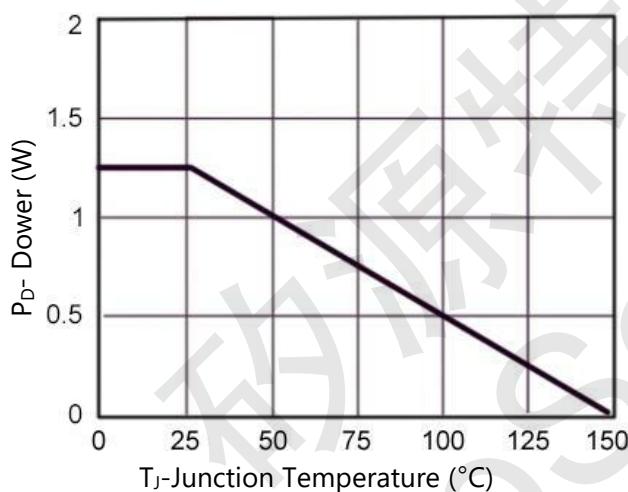


Figure 4. Drain Current

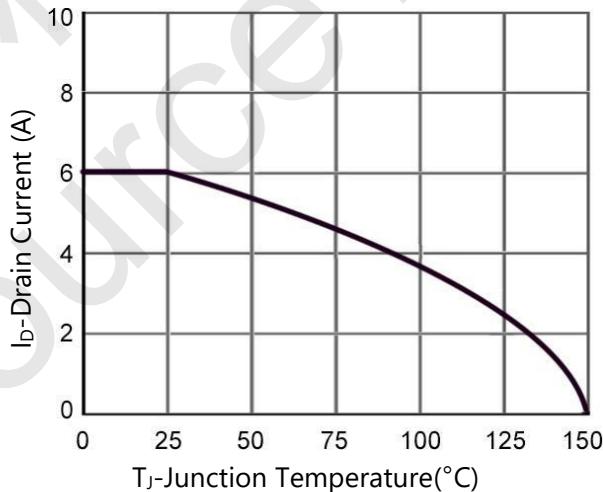


Figure 5. Output Characteristics

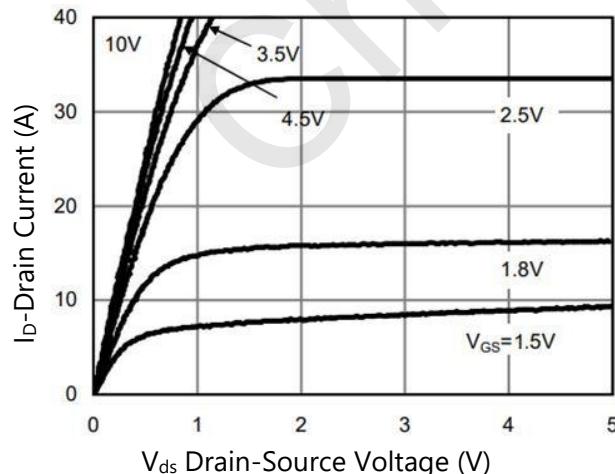
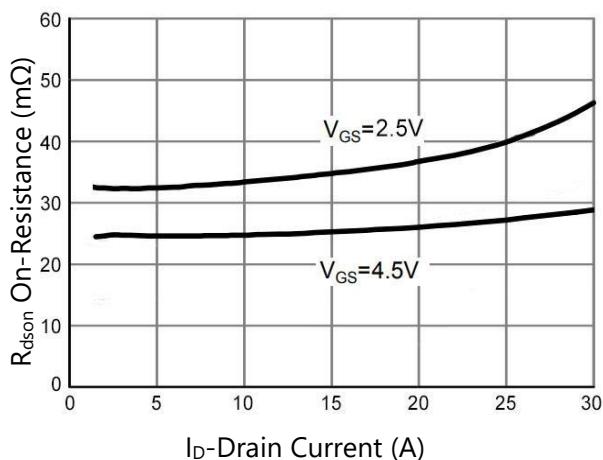


Figure 6. R\_{ds(on)} vs Drain Current





## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 7. Transfer Characteristics

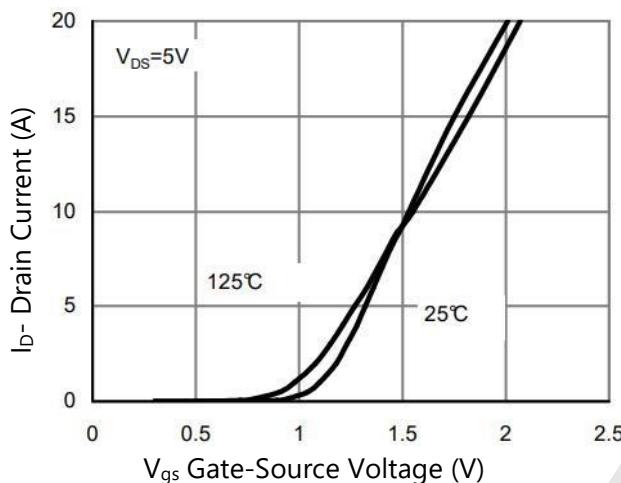


Figure 8.  $R_{dson}$  vs Junction Temperature

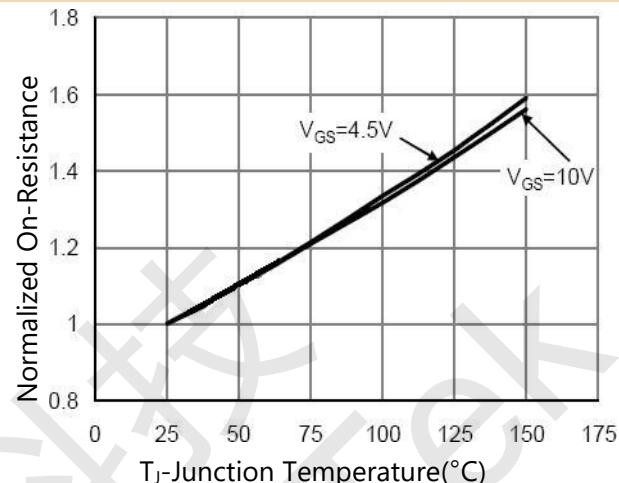


Figure 9.  $R_{dson}$  vs  $V_{gs}$

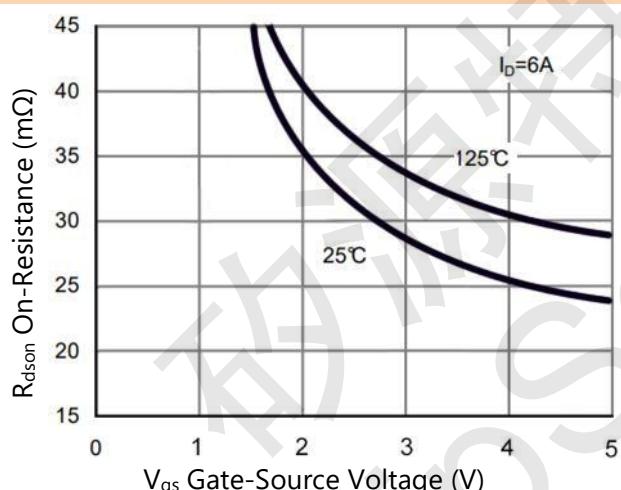


Figure 10. Capacitance vs  $V_{ds}$

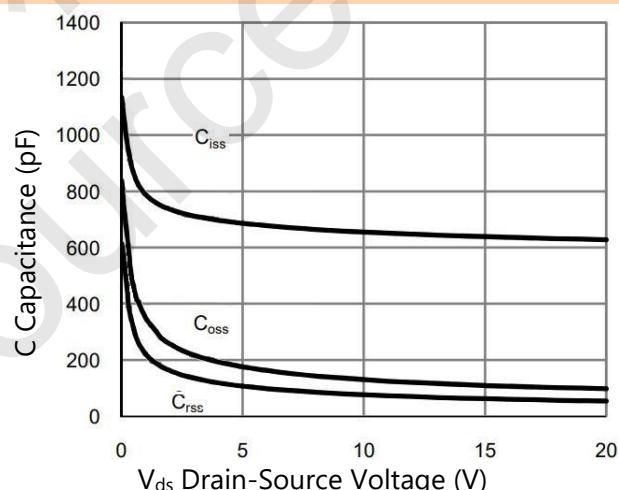


Figure 11. Gate Charge

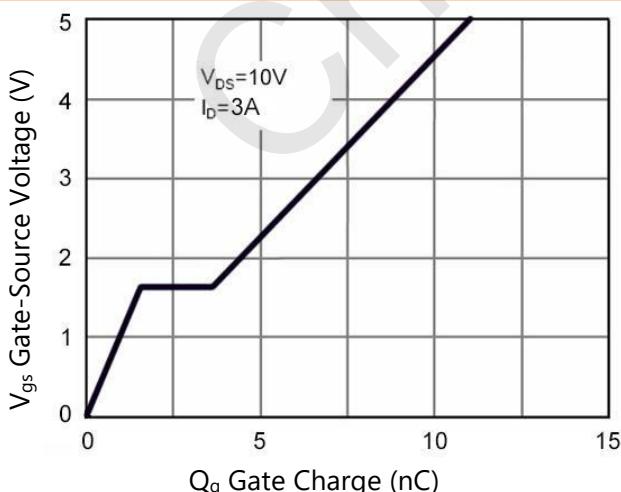
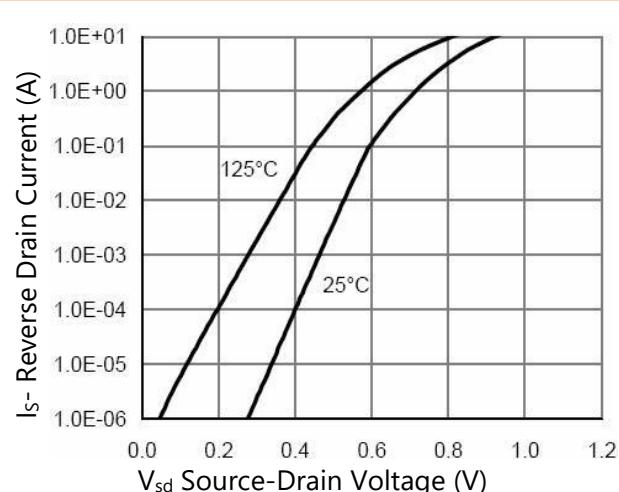


Figure 12. Source-Drain Diode Forward





## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 13. Safe Operation Area

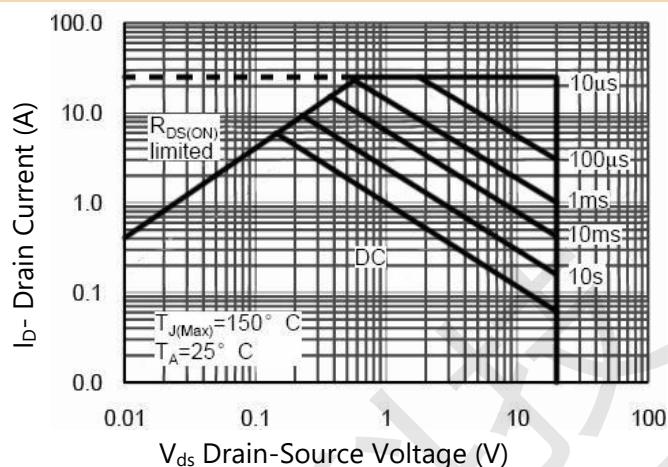
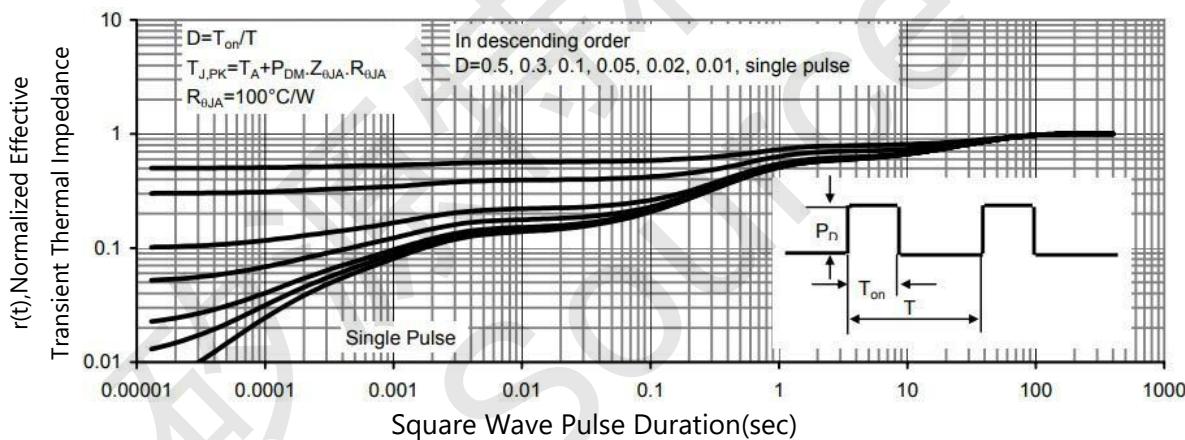


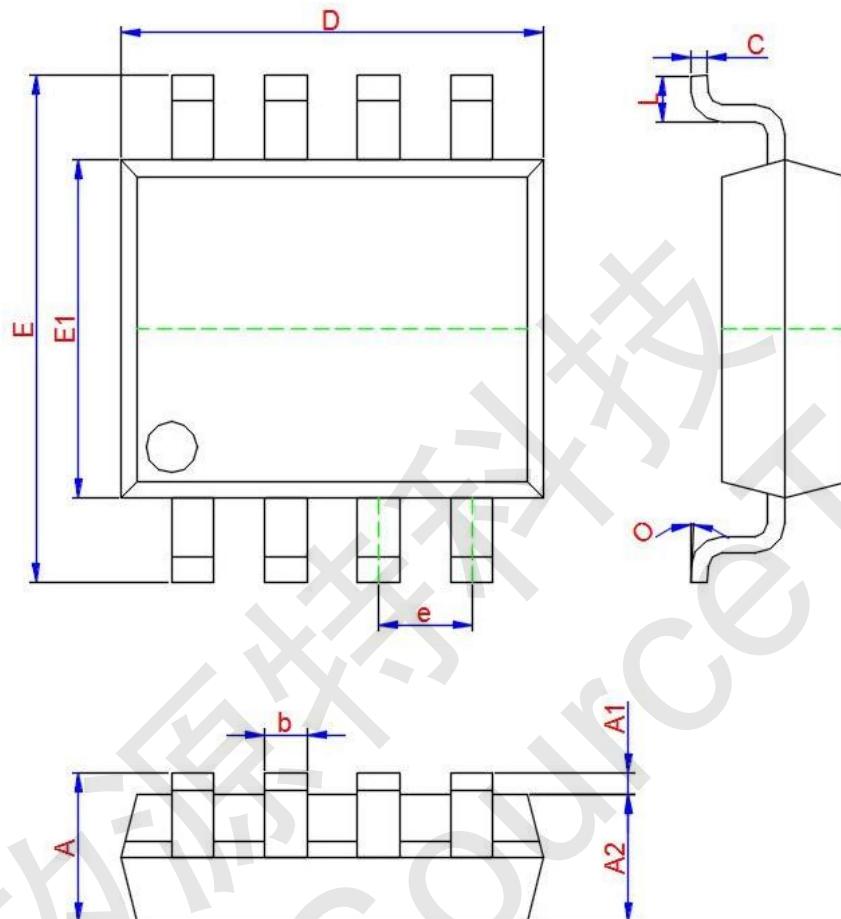
Figure 14. Normalized Maximum Transient Thermal Impedance





 PACKAGE INFORMATION

SOP-8



Symbol	Dimensions In Millimeters		
	Min.	Typ.	Max.
A	1.350	1.550	1.750
A1	0.100	0.175	0.250
A2	1.350	1.450	1.550
b	0.330	0.420	0.510
c	0.170	0.210	0.250
D	4.700	4.900	5.100
e	1.270 TYP.		
E	5.800	6.000	6.200
E1	3.750	3.900	4.050
L	0.400	0.835	1.270
O	0°	4°	8°